

Chemical content 74AHCT123APW-Q100



Type number	Package	Package description	Total product weight
74AHCT123APW-Q100	SOT403-1	TSSOP16	60.43682 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935300987118	5	1	260	30 s	1	235	20 s	3	Bangkok, Thailand; Nijmegen, Netherlands; Suzhou, China	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.13236	77.86000	0.21901
		Polymer	Acrylic resin	Proprietary	0.02581	15.18000
		Resin system	Proprietary	0.01183	6.96000	0.01958
		subTotal		0.17000	100.00000	0.28129
Die	Doped silicon	Silicon (Si)	7440-21-3	0.23490	100.00000	0.38867
		subTotal		0.23490	100.00000	0.38867
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	19.31317	97.47000	31.95597
		Iron (Fe)	7439-89-6	0.47555	2.40000	0.78685
		Phosphorus (P)	7723-14-0	0.00594	0.03000	0.00984
		Zinc (Zn)	7440-66-6	0.01981	0.10000	0.03279
		subTotal		19.81448	100.00000	32.78545
Mould Compound	Additive	Non hazardous	Proprietary	1.86120	4.70000	3.07958
	Filler	Silica fused	60676-86-0	31.28400	79.00000	51.76315
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	2.37600	6.00000	3.93138
	Pigment	Carbon black	1333-86-4	0.07920	0.20000	0.13105
	Polymer	1.4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	1.58400	4.00000	2.62092
		Non hazardous	Proprietary	1.62360	4.10000	2.68644
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.79200	2.00000	1.31046
	subTotal		39.60000	100.00000	65.52298	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.01509	3.00000	0.02497
		Nickel (Ni)	7440-02-0	0.46425	92.30000	0.76816
		Palladium (Pd)	7440-05-3	0.01559	3.10000	0.02580
		Silver (Ag)	7440-22-4	0.00805	1.60000	0.01332
		subTotal		0.50298	100.00000	0.83225
Wire	Pure metal	Copper (Cu)	7440-50-8	0.11446	100.00000	0.18938
		subTotal		0.11446	100.00000	0.18938

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